Texas Instruments Inc. (DUNS# 00-732-1904)
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Distribute - RoHS and IEC 62474 DB
06/09/2022

Details for "TLV76750DRVR"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
TLV76750DRVR	NIPDAUAG	Level-2-260C-1 YEAR	Ext-Mfg	DRV 6	2x2x0.75	8.5

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS REACH		Green	IEC 62474 DB	
Yes	Yes	Yes	Yes	

Component Information

				Homoge	neous Material Level	Component Level	
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.021695	96.701582	967016	0.256416	2564
Precious Metals	Gold	7440-57-5	0.000144	0.641854	6419	0.001702	17
Precious Metals	Palladium	7440-05-3	0.000596	2.656563	26566	0.007044	70
Sub-Total			0.022435	100	1000000	0.265162	2652
Die Attach Adhesive	-						
Precious Metals	Silver	7440-22-4	0.125077	85.499935	854999	1.478301	14783
Thermoplastics	Ероху	85954-11-6	0.021212	14.500065	145001	0.250707	2507
Sub-Total			0.146289	100	1000000	1.729008	17290
Lead Frame		•					
Copper and Its Alloys	Copper	7440-50-8	3.802773	97.507	975070	44.945456	449455
Copper and Its Alloys	Iron	7439-89-6	0.08775	2.25	22500	1.037128	10371
Copper and Its Alloys	Phosphorus	7723-14-0	0.004875	0.125	1250	0.057618	576
Precious Metals	Silver	7440-22-4	0.001092	0.028	280	0.012906	129
Zinc and Its Alloys	Zinc	7440-66-6	0.00351	0.09	900	0.041485	415
Sub-Total			3.9	100	1000000	46.094594	460946
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.04865	97.3	973000	0.575001	5750
Precious Metals	Gold	7440-57-5	0.00015	0.3	3000	0.001773	18
Precious Metals	Palladium	7440-05-3	0.00105	2.1	21000	0.01241	124
Precious Metals	Silver	7440-22-4	0.00015	0.3	3000	0.001773	18
Sub-Total			0.05	100	1000000	0.590956	5910
Mold Compound	-	-					
Other Inorganic Materials	Fused Silica	60676-86-0	3.58502	90.500002	905000	42.371806	423718
Other Plastics and Rubber	Carbon Black	1333-86-4	0.019807	0.500007	5000	0.234101	2341
Thermoplastics	Ероху	85954-11-6	0.356521	8.999992	90000	4.213767	42138
Sub-Total			3.961348	100	1000000	46.819674	468197
Semiconductor Device	-					-	
Ceramics / Glass	Doped Silicon	7440-21-3	0.38079	100	1000000	4.500605	45006
Sub-Total			0.38079	100	1000000	4.500605	45006
Total			8.460862			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**. See Glossary of Terms for more details.

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

For an explanation of the methods used to determine material weights, See Product Content Methodology

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

For additional information, please contact TI customer support.

Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality For further environmental statements, please go to www.ti.com/ecoinfo Created on: 06/09/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in http://www.ti.com/lit/pdf/szzq088

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.